

2013 法人說明會

2013 Investor Meeting

華立集團

Wah Lee Group Worldwide Offices



TSE Ticker : 3010 TT
<http://www.wahlee.com>

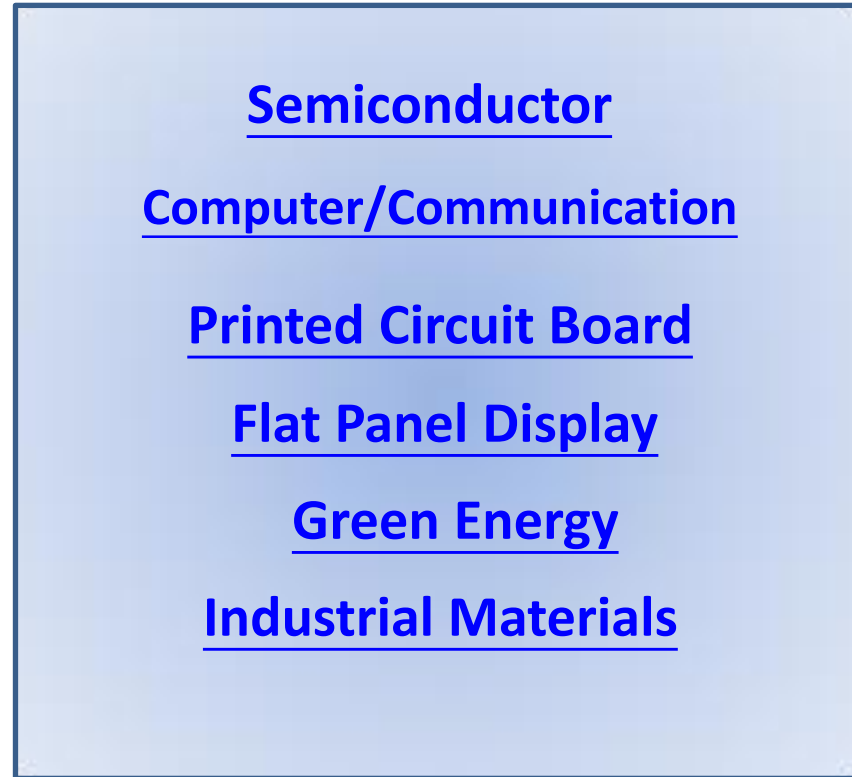
March 28, 2013

內容大綱 - Agenda

- ✦ 華立集團介紹
Wah Lee Group Introduction
- ✦ 2.5級產業介紹
2.5 G Introduction
- ✦ 合併2012年營運報告
Consolidate 2012 Income Statement
- ✦ 產品及產業發展趨勢
Product and Industry Development
- ✦ 生物醫療佈局規劃
Biomedical Industry Roadmap and Strategic Plan
- ✦ Q&A

Wah Lee Group

Leading HI-TECH solutions integrator
and raw materials provider



Product Extension in
Local Markets

Chang Wah

IC Lead Frame
IC Packaging & Test
Materials & Equipment

Nagase Wah Lee

GE Engineering
Plastics

ORC Technology

ORC Exposure
M/C & Lamp

Asahi Kasei Wah Lee

High-end Dry Film

Product Extension Into International Markets

Wah Lee Tech
(Singapore)

Wah Lee Japan
(Tokyo)

Wah Lee Korea
(Seoul)

Raycong
(Southern China
& Hong Kong)

Shanghai
Yi Kang
(Eastern China)

Chengdu
Hua Gang
(Western China)

Value Added Services

Wah Hong

Optical Film
High Performance Material
Hand-Set Component
Automated Equipment

SIP Chang Hong

Sun Hong

Ningbo SIP
Chang Hong

Xiaman Guang Hong

Qingdao Chang Hong

Gunze Wah Hong

Ito Film
Touch Panel

2.5G Service Industry/2.5級製造服務業

一分鐘解讀 2.5級產業

什麼是2.5級產業？

一般稱製造業為第2級產業，服務業為第3級產業，2.5級產業則是介於中間，為建立在製造業上的服務產業。許多大廠要建新廠或跨入新領域，都必須尋求2.5級業者的協助。

Source: 天下雜誌444期, April, 2010

緊抓下游

2.5級產業的另一手抓住下游各行各業製造業客戶，導入最新製程技術，並幫忙客戶改善生產線效率。

為何現在2.5級產業這麼重要？

台灣生產要素相對競爭力比其他新興國家弱，單純製造業外移已不可避免，若要保持一部份製造業在台灣，必須要跟服務業做結合。

哪些人是2.5級產業？

過去，2.5級產業都被歸類為黑手、賣

緊抓上游

2.5級產業像是八爪章魚，掌握市場兩端商情，一手抓住上游成千上百的零組件與材料供應商，隨時提供上游最即時市場資訊，提早開發新產品。

台灣產業結構正在進入退2（製造業）進3（服務業）的大轉型，2.5級業者，將如何影響產業發展？如何趁勢賺錢？
文／江逸之 攝影／邱劍英 插圖／張培音

2.5級產業 - 連結上游供應商以及下游製造業客戶

- 對於上游供應商，2.5級產業掌握了市場兩端的商情，能提供上游最即時的市場資訊，做為新產品開發上的參考
- 對於下游製造業客戶，2.5級產業協助導入最新製程技術，並提供解決方案改善生產效率
- 華立成功之關鍵：「跨業整合技術能力強」以及「永遠走在客戶前面」

Connecting upstream suppliers with downstream customers:

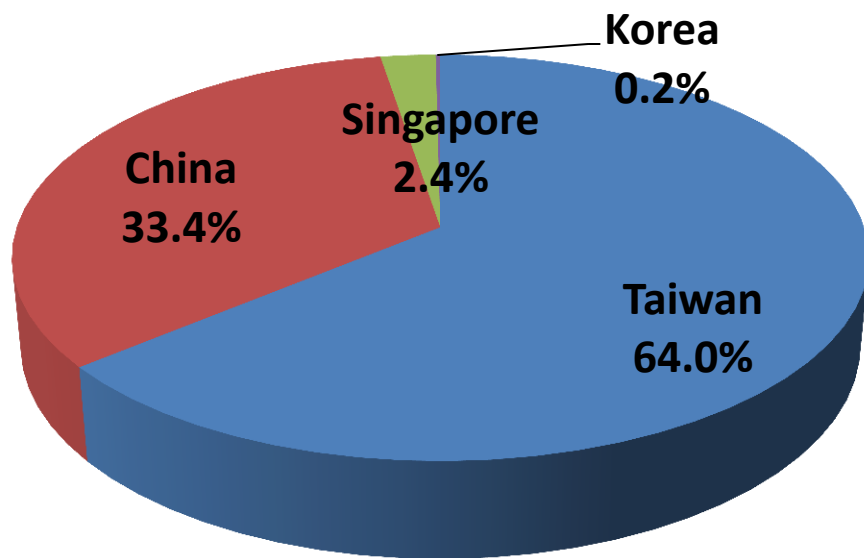
- Providing real-time market information for new product development considerations
- Assisting customers in implementing latest technological solutions to improve production efficiency
- Wah Lee's Key Success Factors: Ability to provide total solution across industries and always being ahead of customers in technology development.

合併 2012 財務報表
Consolidated 2012 Financial
Performance

Region Sales Breakdown 營收區域別資訊

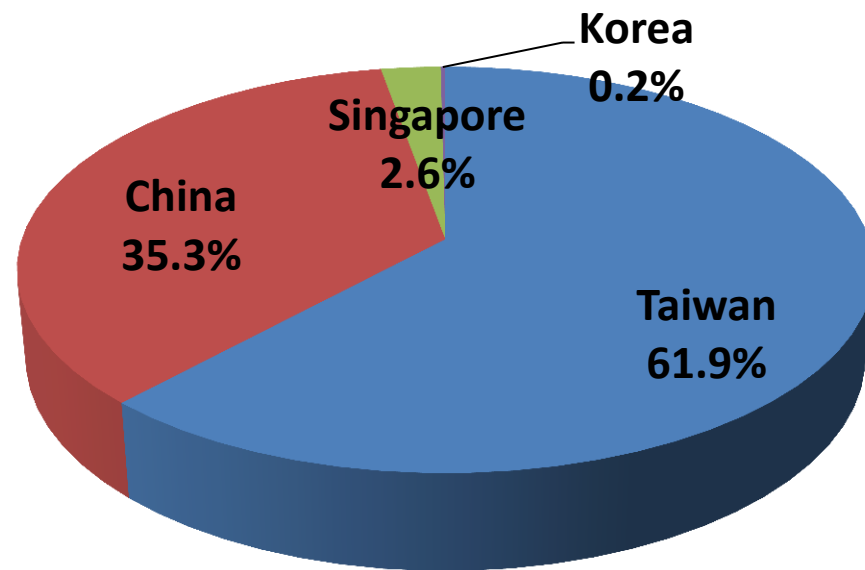
2012

Sales NT\$31.5 Billion



2011

Sales NT\$31.2 Billion



2012 Consolidated Income Statement 合併損益表

Unit: NT\$ million	2012 (CPA)	2011 (CPA)	YoY
Net Sales 營收淨額	31,545.3	31,224.5	1%
Gross Profit 銷貨毛利	2,857.9	2,821.8	1%
Gross Margin 毛利率	9.1%	9.0%	0.0%
Op. Expense 營業費用	2,023.5	1,881.9	8%
Op. Profit 營業利益	834.4	939.9	-11%
Non-op. Profit 業外收支	481.1	410.5	17%
L-T Investment Income 長投收益	417.5	264.3	58%
Disposal Gain 處分利益	2.6	37.4	-93%
Others 其他	60.9	108.3	-44%
Pre-tax Profit 稅前利潤	1,315.5	1,350.3	-3%
Net Income 稅後淨利	981.1	952.2	3%
After-tax EPS	4.24	4.12	3%

* Consolidated entities include: Wah Lee Taiwan and China Subsidiaries (Raycong, Shanghai YiKang), Wah Lee Japan, Wah Lee Tech(Singapore), and Wah Lee Korea.

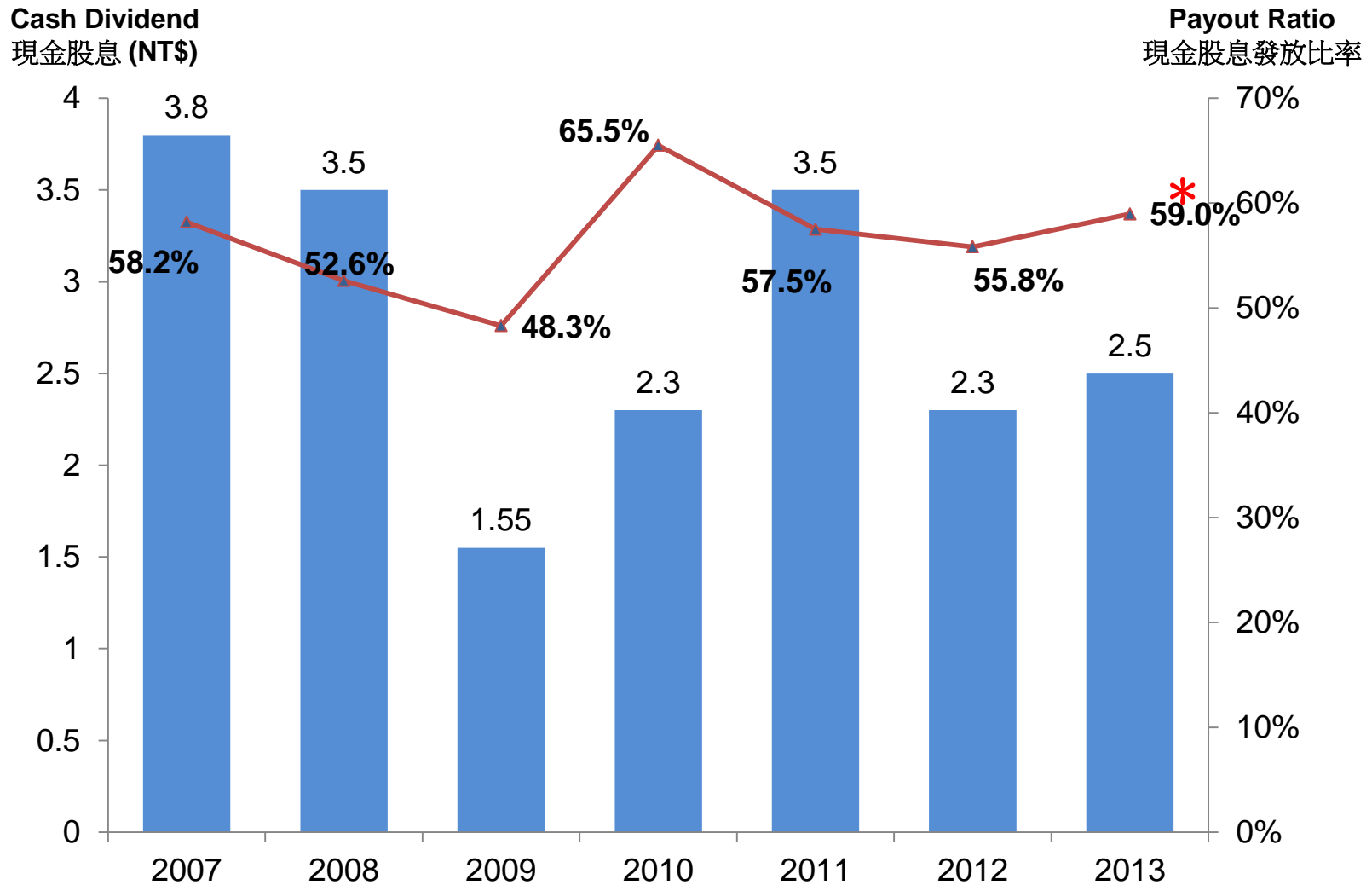
*上述合併報表主體，包含華立台灣、大陸子公司(華港香港、上海怡康)，華立日本，華立新加坡，及華立韓國。

2012 Long Term Investments 長期投資收益

Unit: NT\$ thousand

Long-term Investments 轉投資事業	Product Lines 主要產品線	Holding % 持有比例 %	2012 Earnings Recognized 長投收益
Chang Wah Electromaterials Inc. 長華電材	Semiconductor Packaging and Testing Materials	28	198,518
Nagase Wah Lee Plastics 長華塑膠	SABIC Engineering Plastics	40	137,764
Wah Hong Industrial Corp. 華宏新技	Optical Film, High Performance Plastic Compound, Heat Dissipation Solution, VCM Actuator	24	71,531
ORC Wah Lee Technology Corp. 華展光電	ORC Exposure Machine and Lamps	35	9,729
Total			417,542

Dividend Policy 股利政策



* 當年分派之股利來自於前一年之獲利。Dividends are distribution of prior year's earnings.

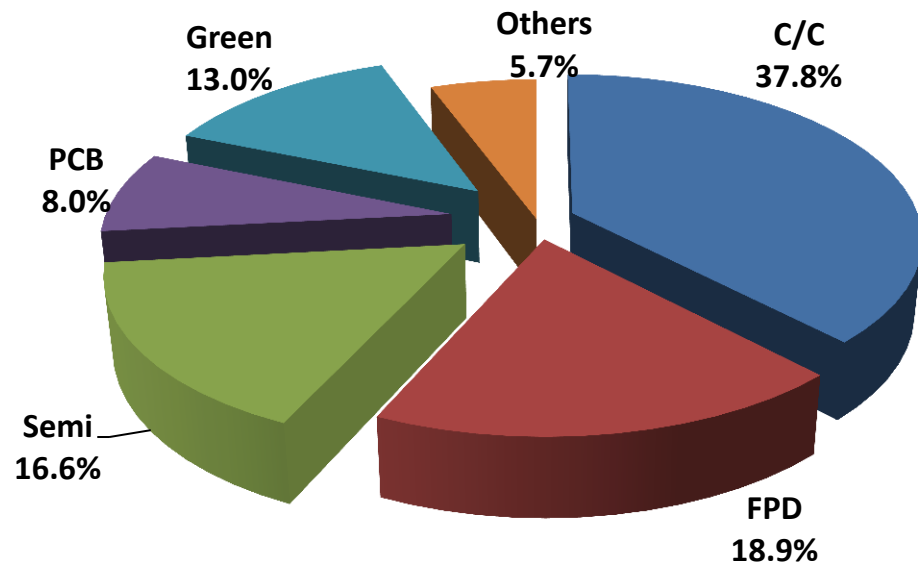
* 2013年股利待股東會決議通過。2013 dividends are subject to the resolution of AGM.

產業及產品發展趨勢
Industry and Product
Developments

Industry Sales Breakdown 營收產業別資訊

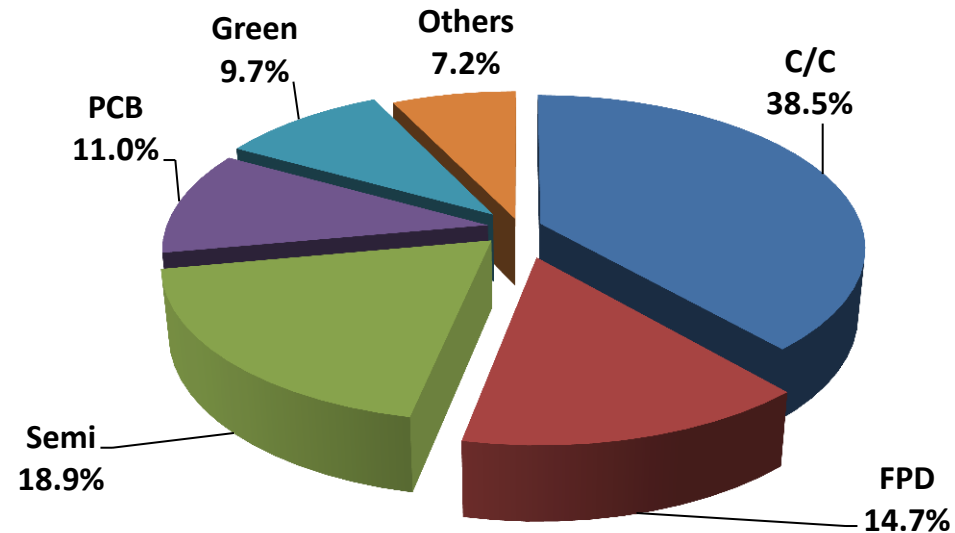
2012/ 01-12

Sales NT\$31.5 Billion



2011/ 01-12

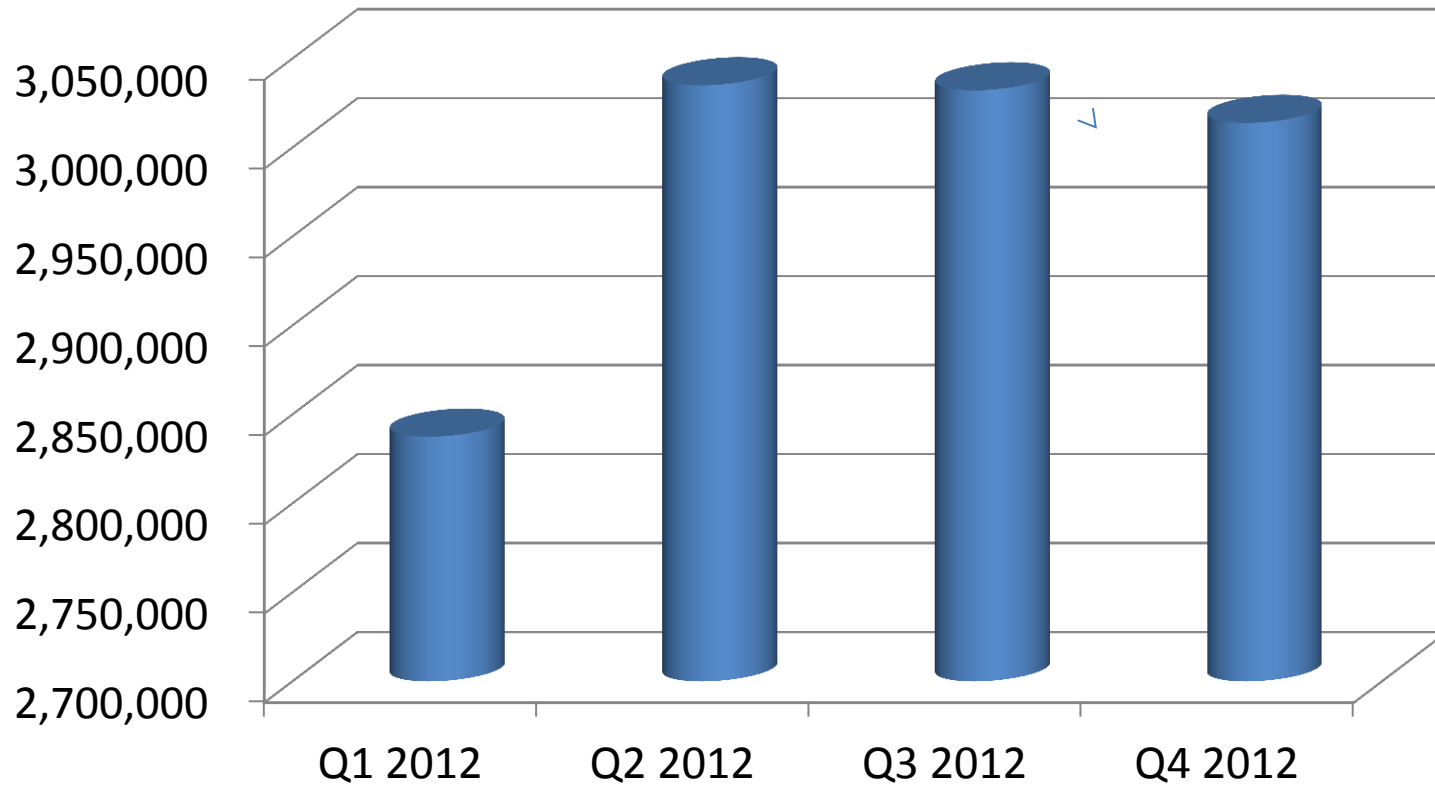
Sales NT\$31.2 Billion



資通訊用高機能塑膠

千元
In thousands

Computer Communication Engineering Plastic



2012 Q 1	2012 Q 2	2012 Q 3	2012 Q 4
2,837,549	3,055,019	3,032,201	3,013,890

高機能工程塑膠近期開發應用領域-電腦機殼

Recent developments in Engineering Plastic- Computer Casing

電腦機殼



高機能工程塑膠近期開發應用領域-家電，醫療 Recent Developments in Engineering Plastics Consumer Electrics, Medical Industry



Coffee machine parts



Slow Juicer parts

醫療 : Glasses frame



高機能工程塑膠近期開發應用領域-食品包裝材

Recent Development in Engineering Plastic - Food Packaging

食品包裝材

多層瓶



藥品包裝



杯類/盤類



軟性包裝



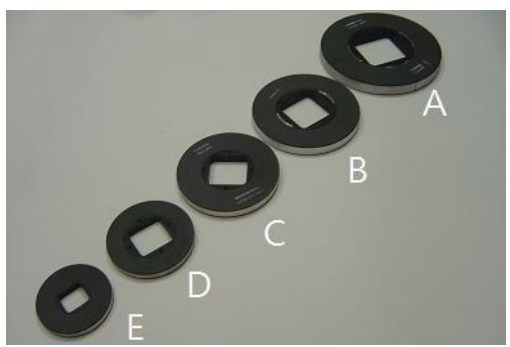
軟管



複合膜

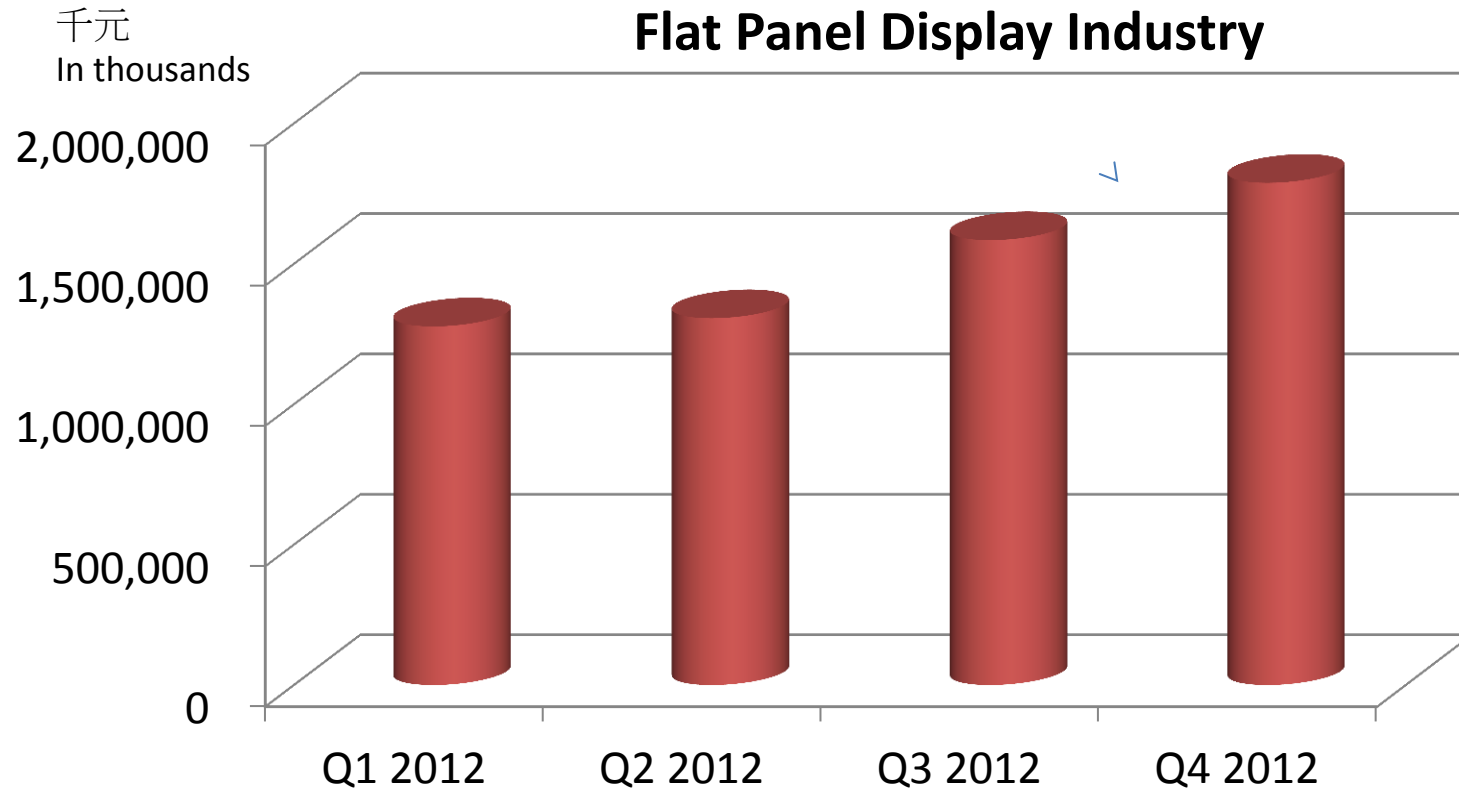


汽車 : PULLEY/WATER PUMP/PISTION/GASKET



平面顯示器產業

Flat Panel Display Industry



2012 Q 1

2012 Q2

2012 Q3

2012 Q4

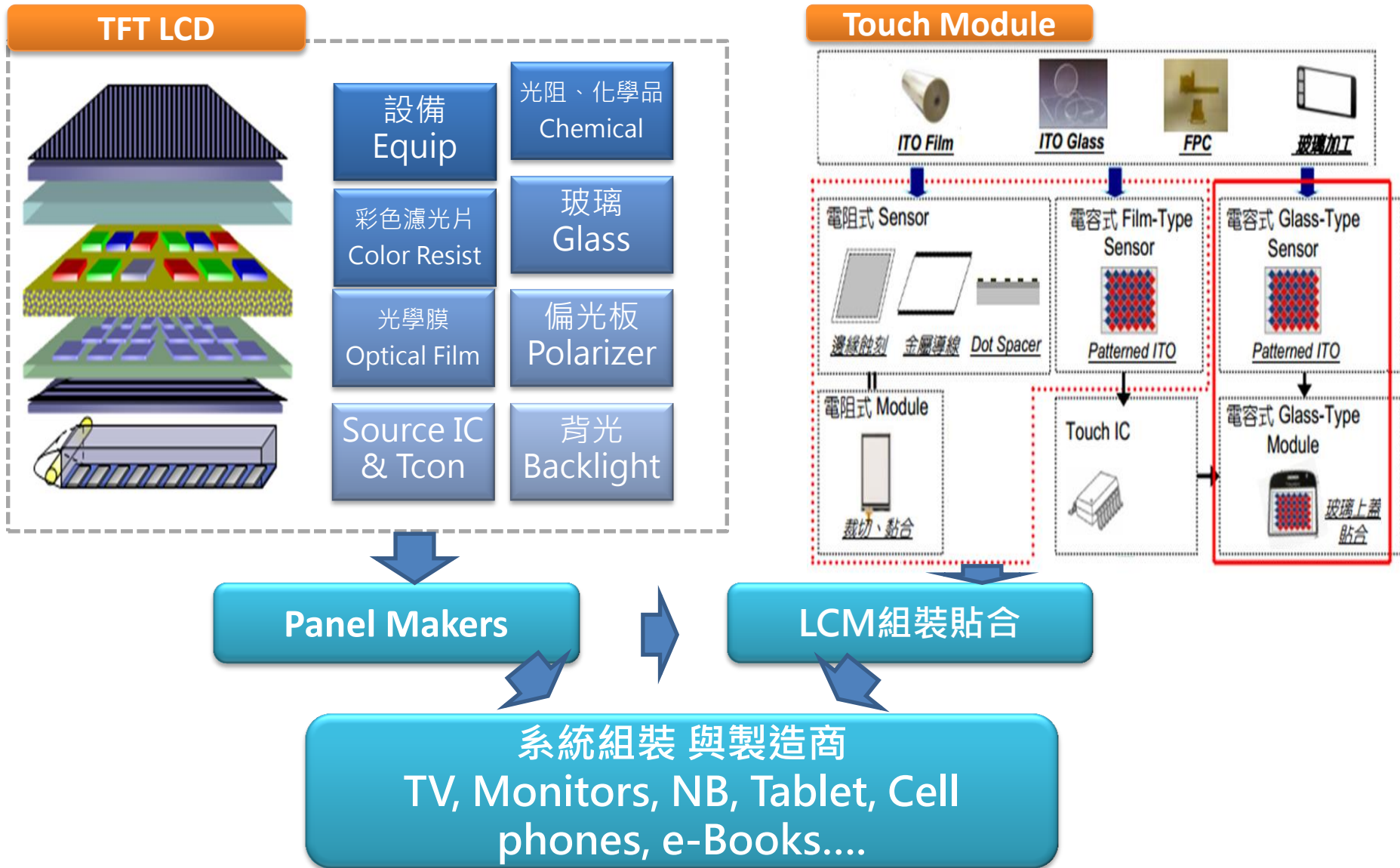
1,277,309

1,306,531

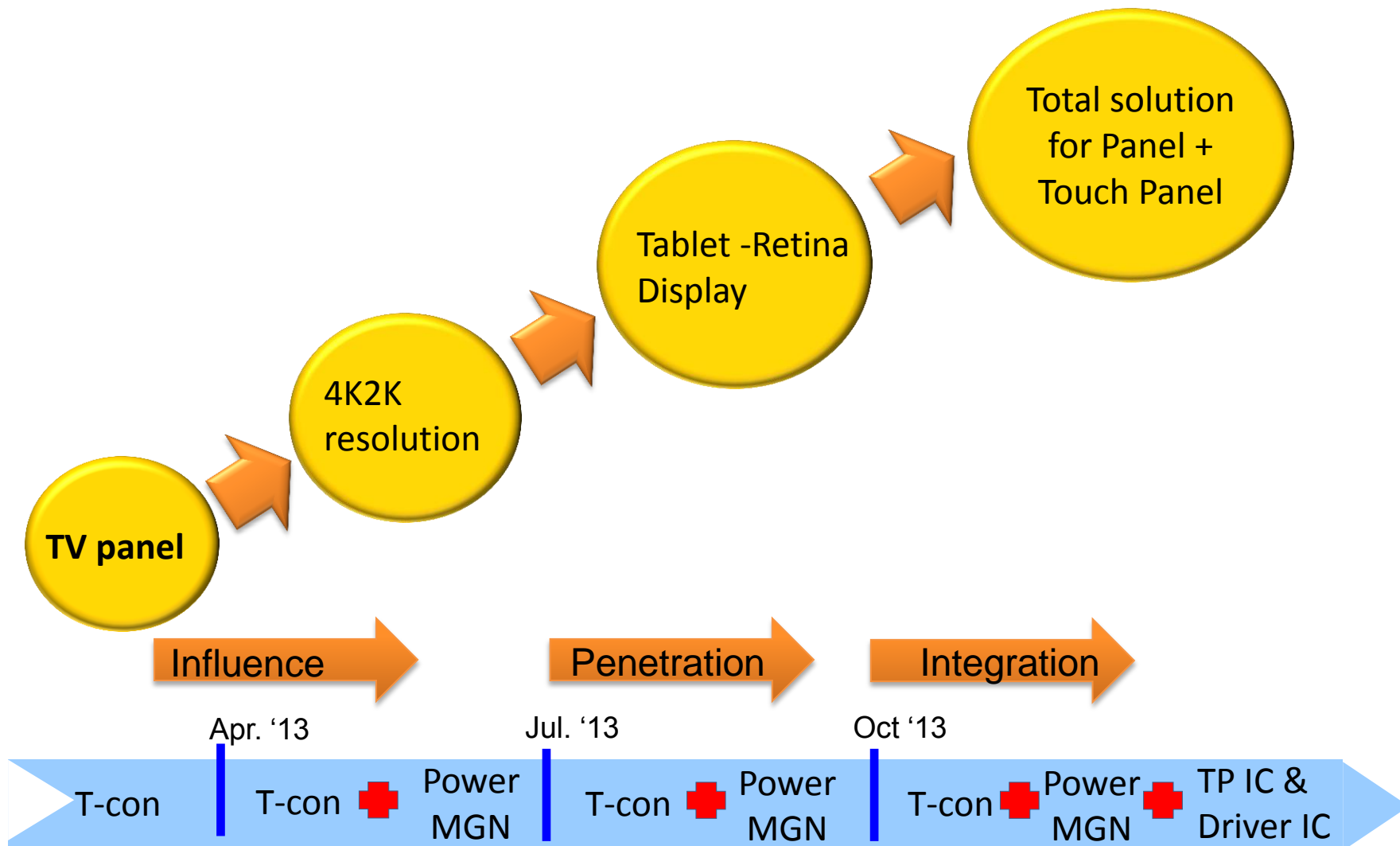
1,584,445

1,788,713

FPD Supply Chain FPD產業鏈 (TFT LCD & TP)



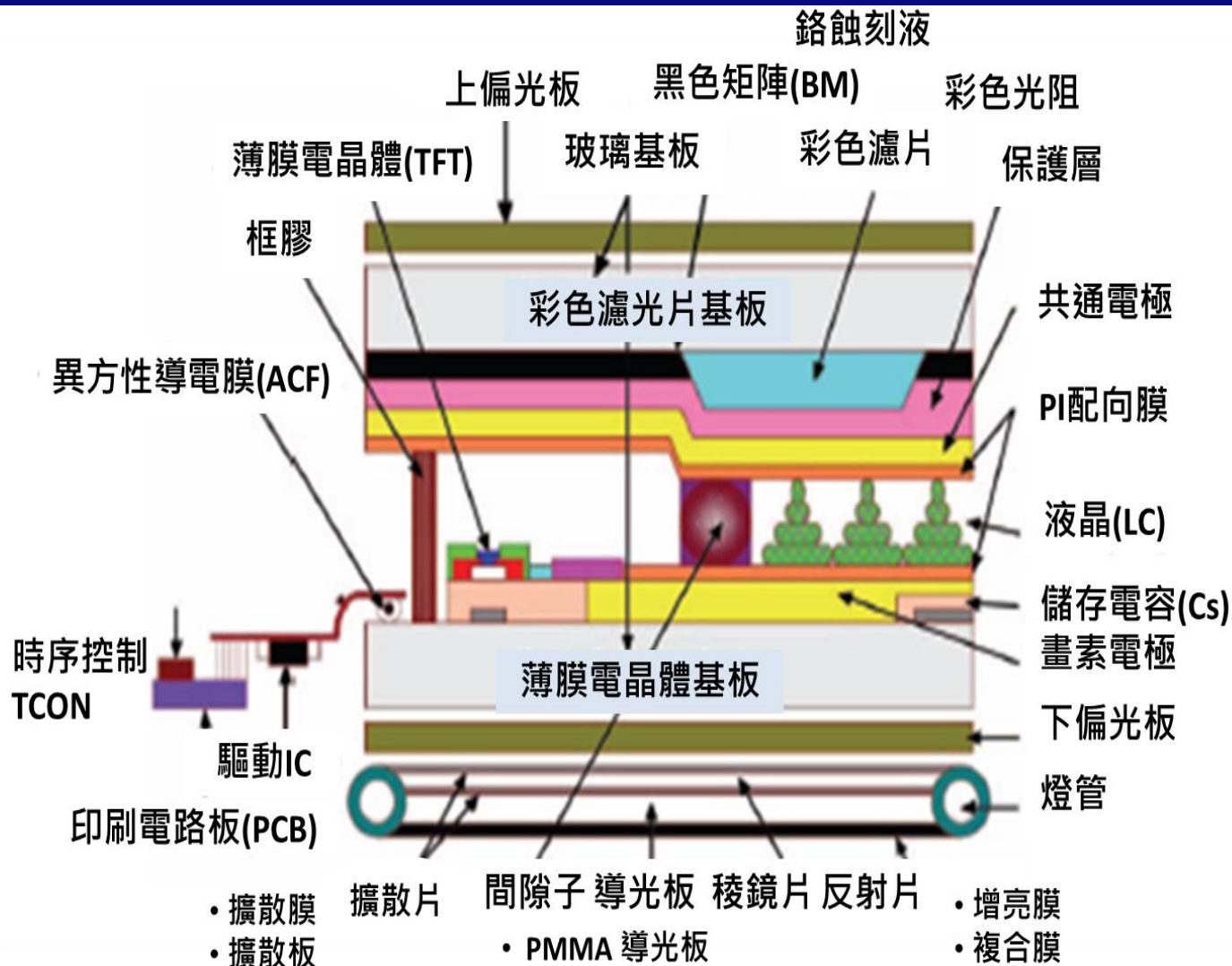
Wah Lee FPD Turnkey Solution 華立FPD成長策略



在LCD TV應用中，華立供應超過九成材料 Wah Lee Provides over 90% of Material used in LCD TV

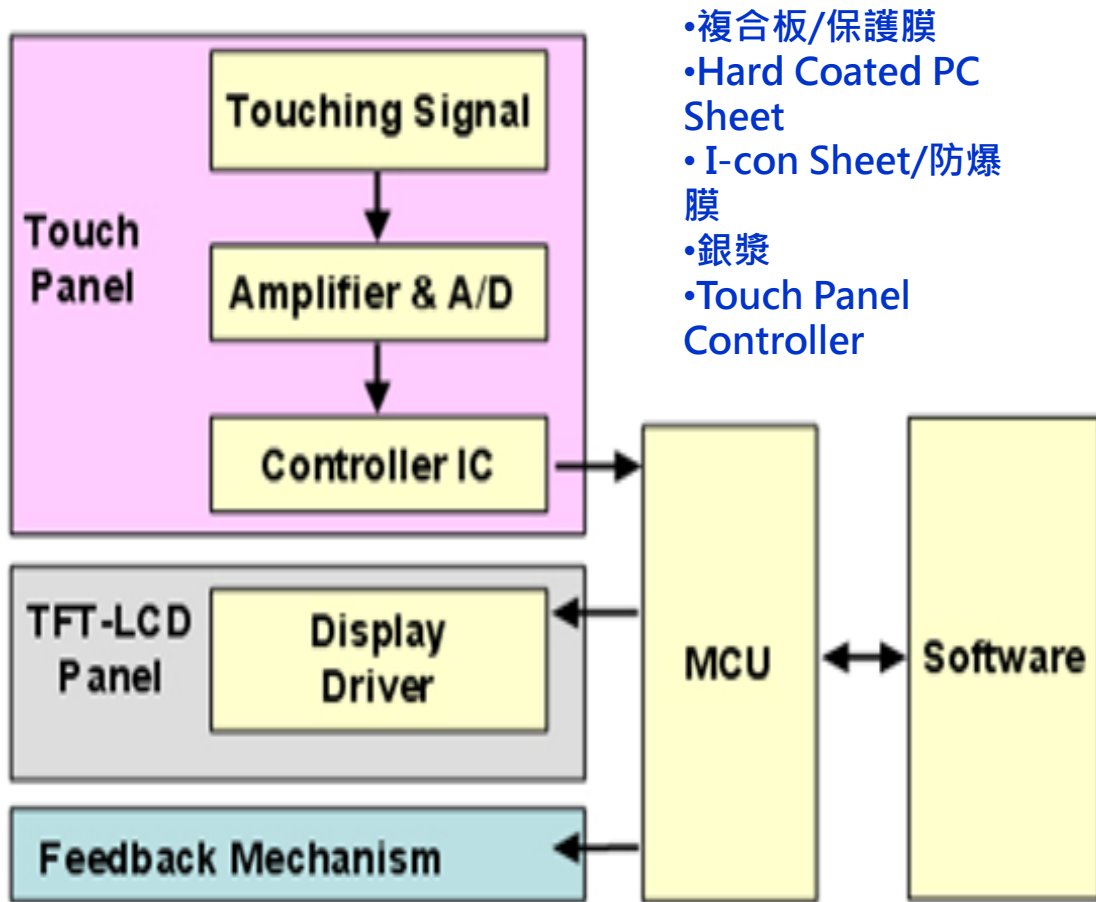
製程設備與耗材
其它製程用化學材
及氣體

- Edge Beam Cleaning : PGME、PGMEA
- Chamber Cleaning : NF3
- 形成 Si 薄膜 : SiH4

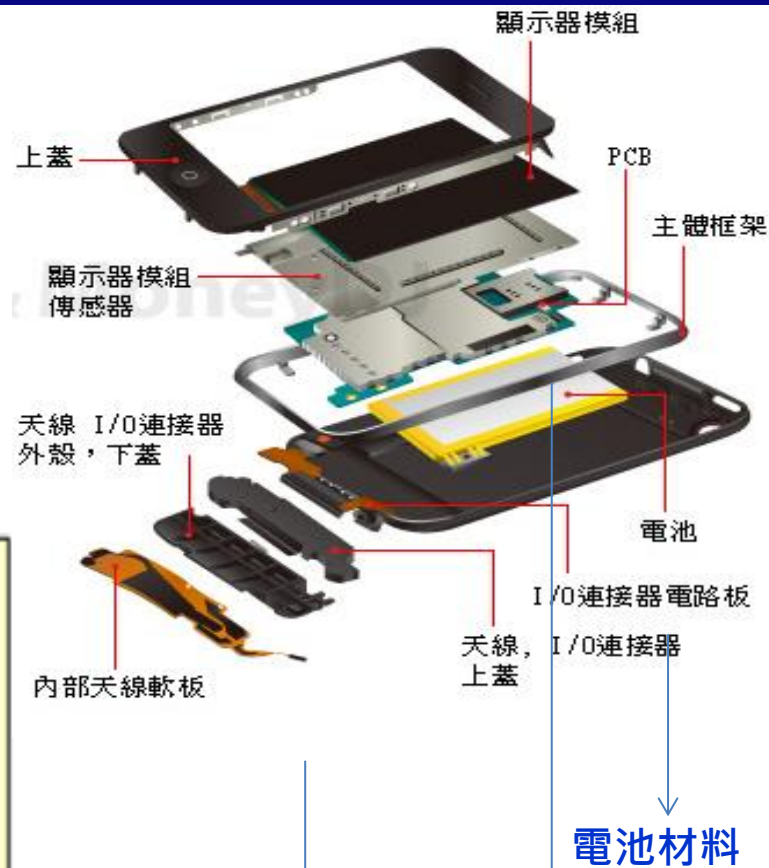


在平板與手機應用中，華立提供超過七成材料

Wah Lee Provides over 70% of material used in FPD and Cell Phone



- 複合板/保護膜
- Hard Coated PC Sheet
- I-con Sheet/防爆膜
- 銀漿
- Touch Panel Controller



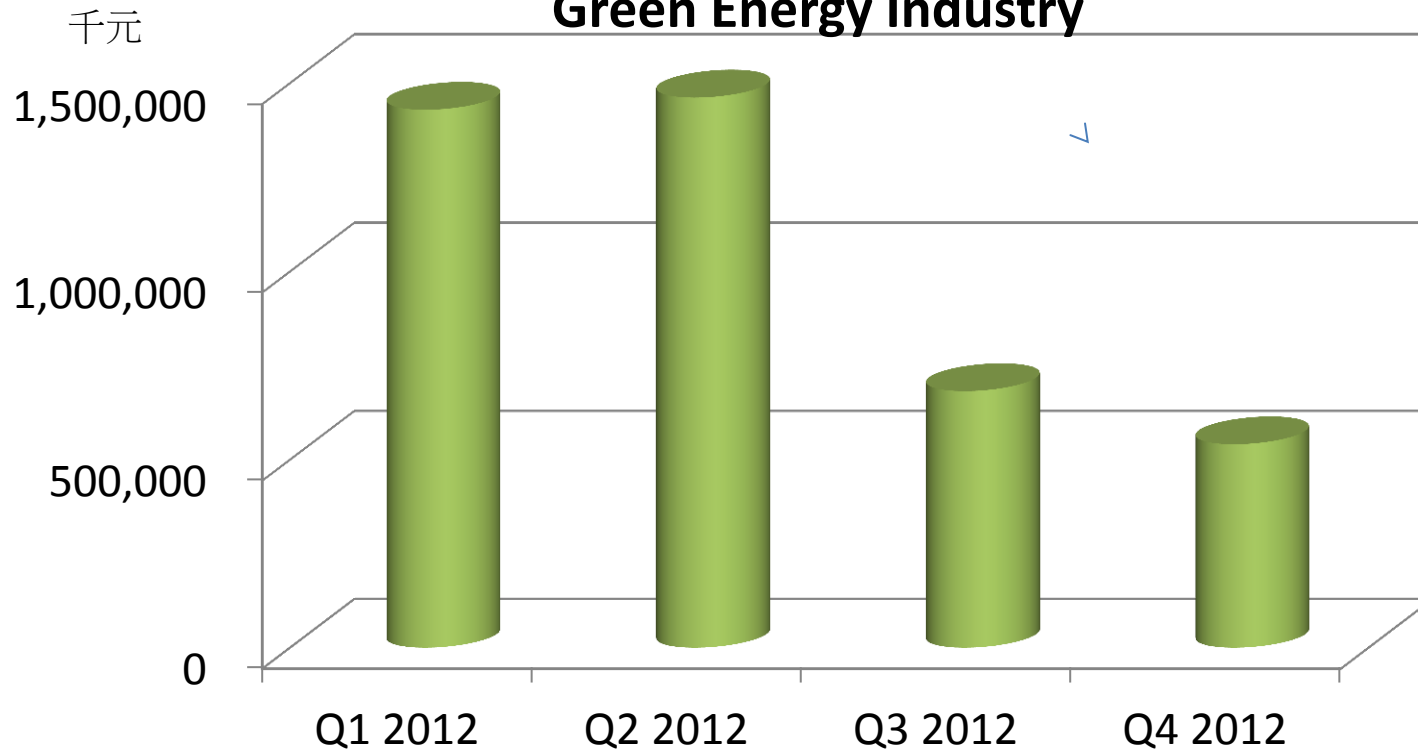
高機能工程 塑膠、碳纖 材料...

電池材料

PCB/軟板材料

綠能光電產業

Green Energy Industry



2012 Q 1

2012 Q2

2012 Q3

2012 Q4

1,429,243

1,461,628

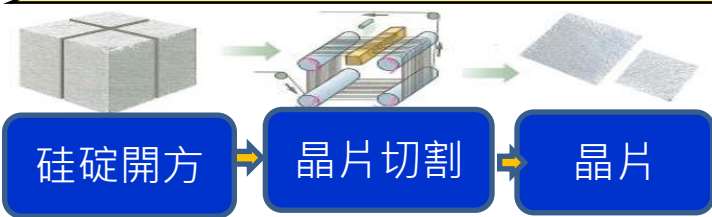
682,358

540,953

Solar Supply Chain

太陽能產業鏈

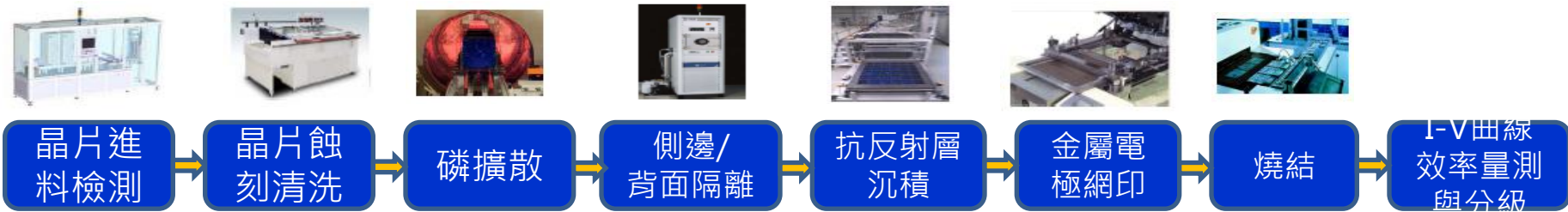
Solar Wafer



• 切割鋼線

- 多晶矽晶片
- 鑫單晶晶片

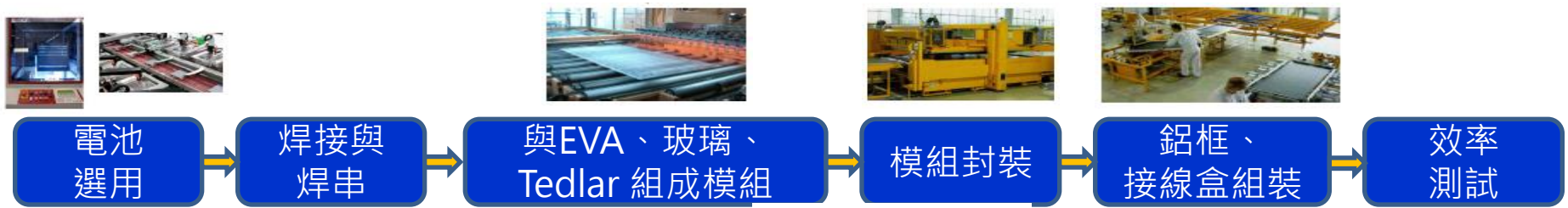
Solar Cell



- NF3
- IC Chemical
- Texture etchant
- POCL3

- NH3
- SiH4
- 銀漿、鋁漿
- 銀/鋁漿

PV Module



- Solar Cell

- Solar Glass
- Backsheet
- EVA sheet

- Junction Box 用PPE

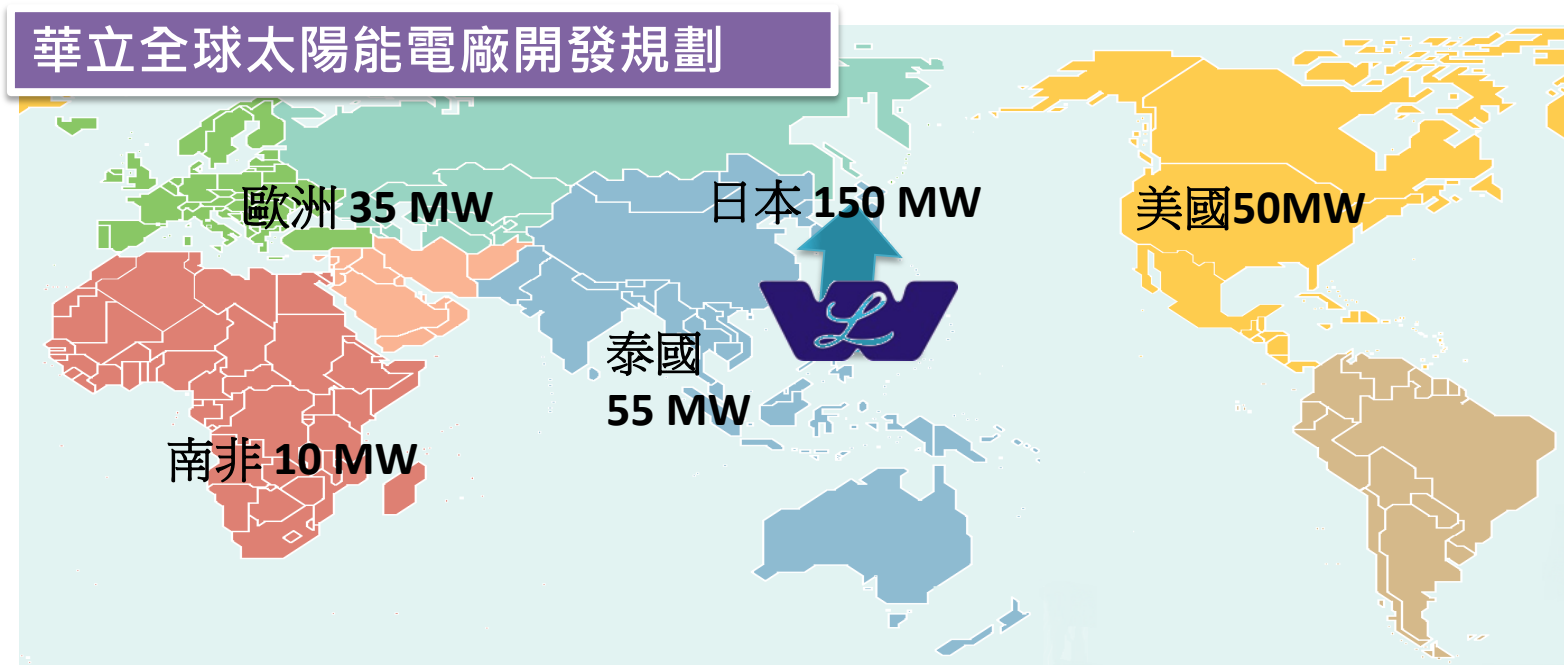
TV System



- 小型太陽能系統
- 電廠

WL's Growth Driver in Solar WL太陽能的成長動能

- 更具彈性的服務模式
 - 除單晶、多晶、銀鋁漿、背板等材料銷售外，進行代工等服務與出海口機會，具備全面產業鏈供應能力
- 海外太陽能電廠營運與開發
 - 具備當地市場開發與建置能力
 - 與金融集團合作取得資金槓桿



LED Supply Chain

LED產業鏈

1. 原始材料合成
2. 蒸餾還原形成多晶
3. 單晶成長單晶棒



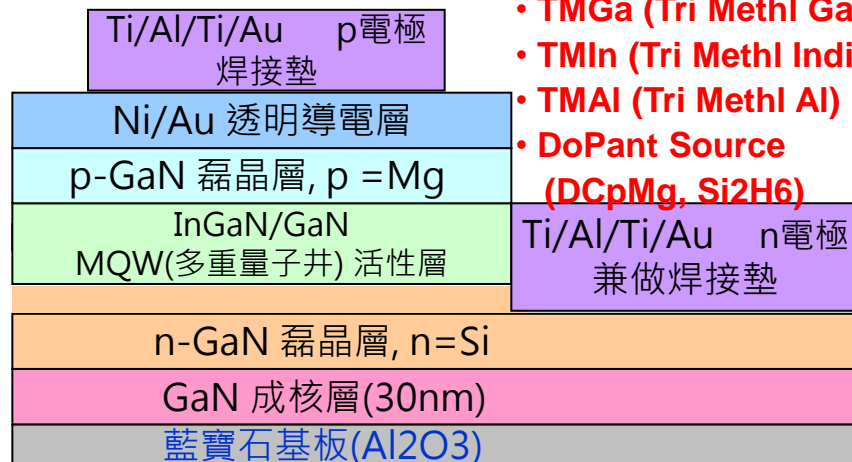
將單晶棒鋸切成片狀晶圓，並加以拋光處理。

- 鑽石切割線、PSS

4. 晶圓/基板

N電極形成區

- AsH₃、PH₃、SiH₄



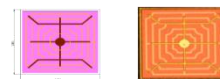
- NH₃、GaAs
- TMGa (Tri Methl Ga)
- TMIIn (Tri Methl Indium)
- TMAI (Tri Methl Al)
- DoPant Source (DCpMg, Si₂H₆)

5. 磊晶成長

6. 晶片製程 (製作電極圖案)

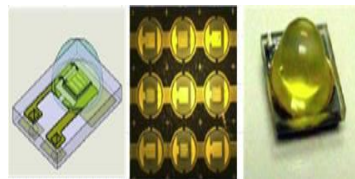
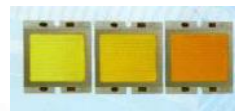
- Du Pont EKC Remover

7. 磊晶晶圓減薄並切割成晶粒



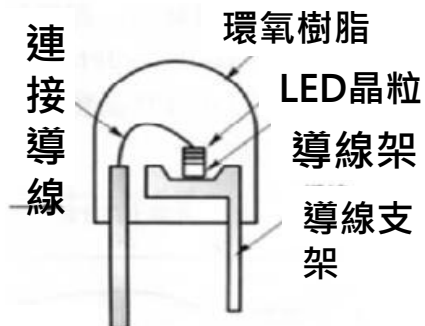
• EMITTER 9. 元件/模組

8. 封裝



10. 半成品/成品

- 構構件
- 燈源/燈具

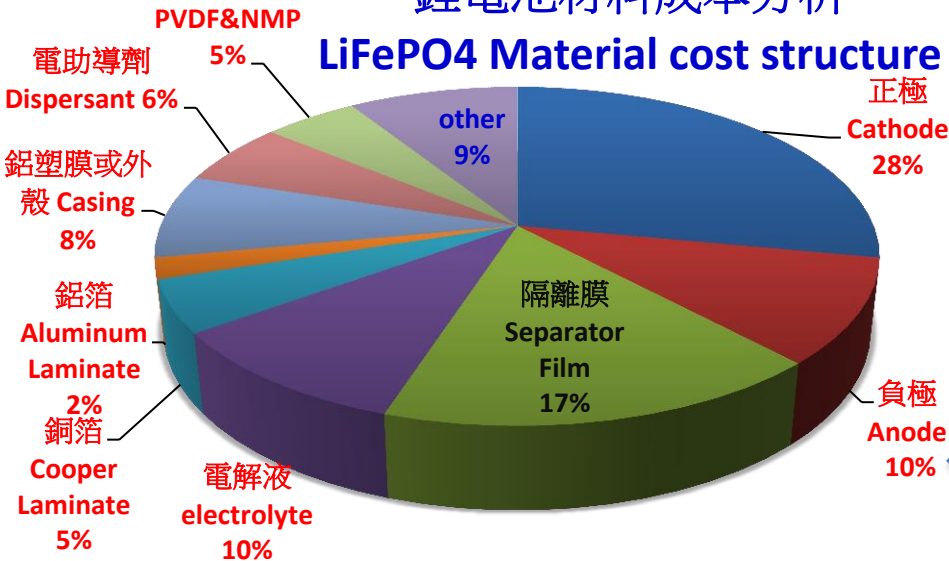


- PA9T、LCP
- 螢光粉 (Fluorescent Powder)
- 封裝材(矽膠、Hybrid、Epoxy)
- JSR LED Material

Products in Rechargeable Battery 二次電池產品

鋰電池材料成本分析

LiFePO4 Material cost structure



動力電池應用



電動車



電動機車



充電站

電池模組



3C電池芯



電動車電池模組



平板電池模組

3C電池應用



平板



智慧型手機



無限充電電池系統



平板電腦

半導體產業

Semiconductor Industry



2012 Q 1

2012 Q2

2012 Q3

2012 Q4

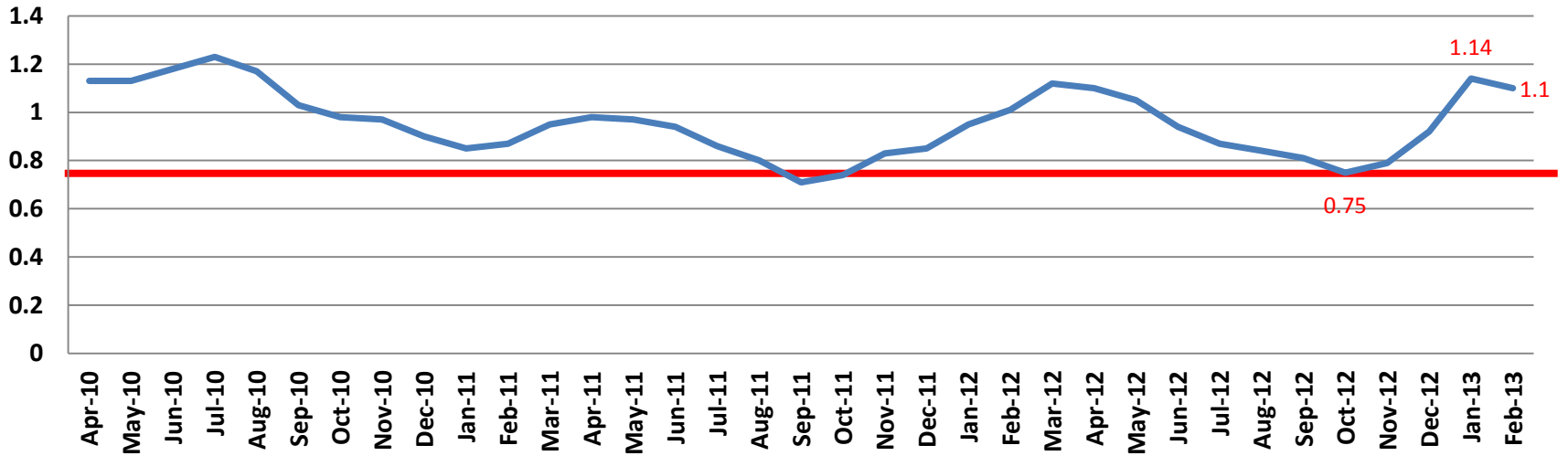
1,198,674

1,389,833

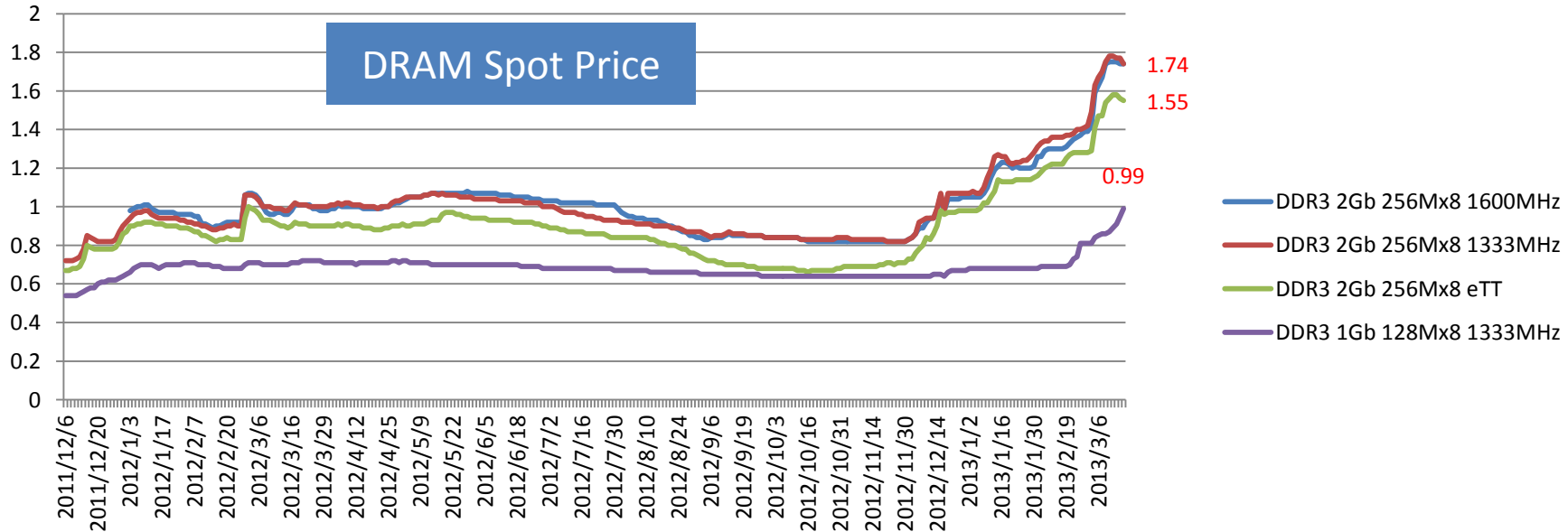
1,356,480

1,294,357

B/B Ratio

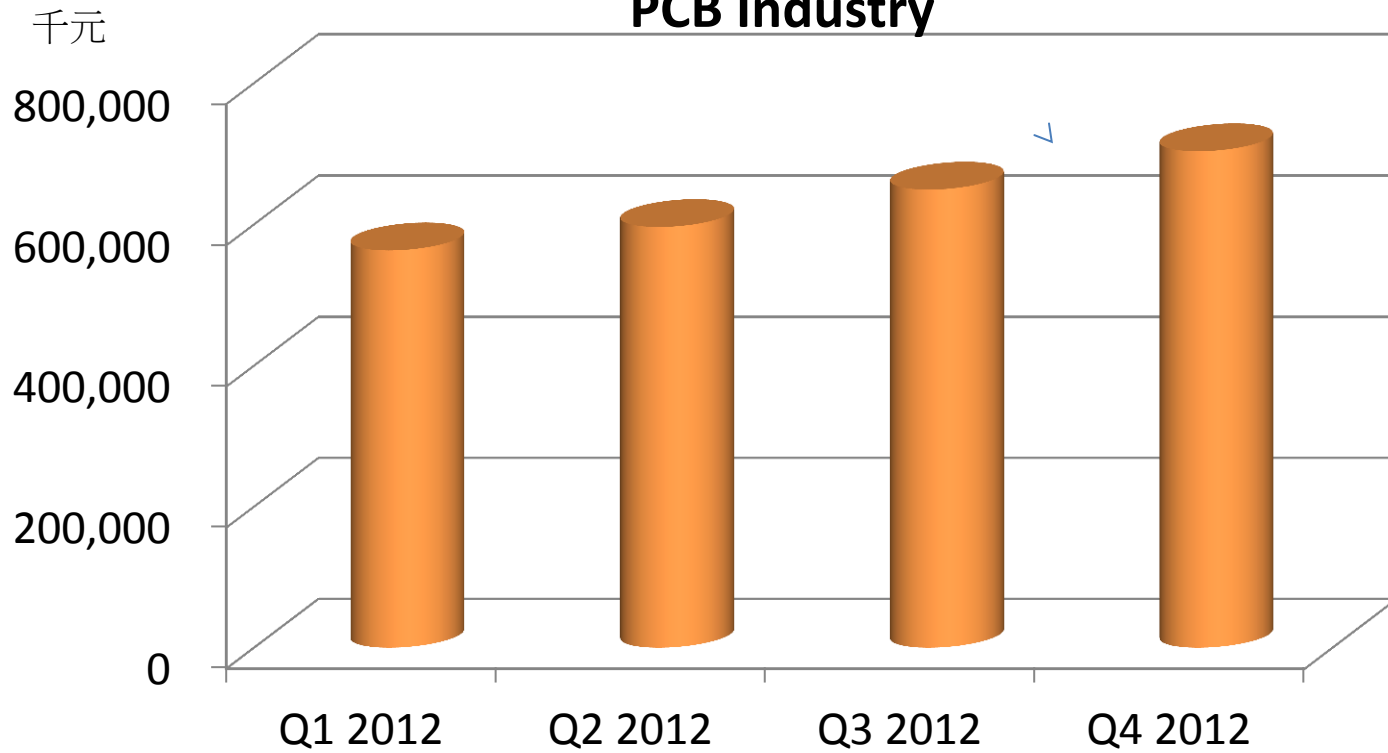


USD



PCB產業

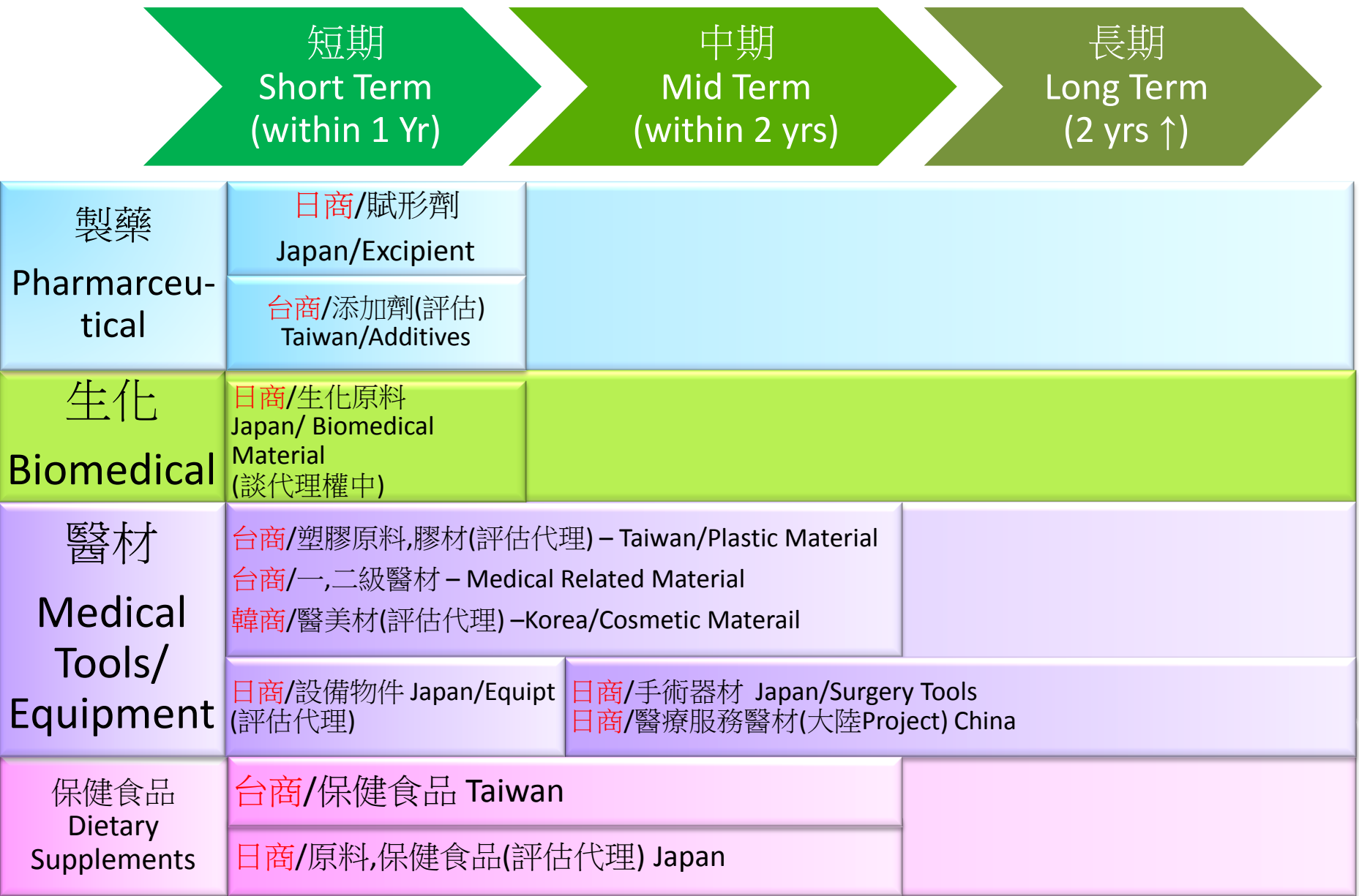
PCB Industry



2012 Q 1	2012 Q 2	2012 Q 3	2012 Q 4
563,180	596,325	649,224	703,552

生物醫療佈局規劃
Biomedical Industry Roadmap
and Strategic Plan

Biotech Roadmap 生化產業發展規劃



Q & A